

# MCNI1214-P48

## L-Band Internally Matched GaN Device

## **Key Features**

■ Operating Frequency: 1.20–1.40 GHz
■ Saturated Output Power (Psat): ≥48.0dBm

Power Gain(Gp): ≥13.0dB
Work Efficiency (η): ≥50%
Port Matching: Zin/Zout = 50 Ω



## **Product Description**

The MCNI1214-P48 is an internal matching GaN device, which adopts advanced co-planar internal matching MCM and thin film circuit technology. The typical working frequency range is 1.20–1.40 GHz.

This device can be used in different RF/Microwave system and subsystem. The high output power level, high efficiency and wide operating temperature range can make application very flexible.

### **Absolute Maximum Ratings (Tc=25°C)**

Parameter	Symbol	Value	Unit
Drain-Source Voltage	Vos	40	V
Gate-Source Voltage	V <sub>G</sub> S	-5	V
Storage Temperature	T <sub>stg</sub>	-65 ~ +150	°C
Channel Temperature	Tch	150	°C

<sup>\*</sup>Not recommended to work under these conditions.

## **Microwave Electrical Characteristics**

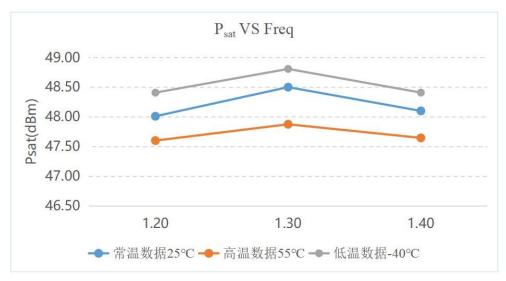
Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Drain Current	ldsr	VDS:32V CW Pin: 35dBm Freq: 1.2~1.4GHZ	-	3.9	-	Α
Saturated Output Power	P <sub>sat</sub>		48	-	-	dBm
Power Gain	Gp		13	-	-	dB
Work Efficiency	η		50	-	-	%
Gain Flatness	ΔG		-0.8	-	0.8	dB

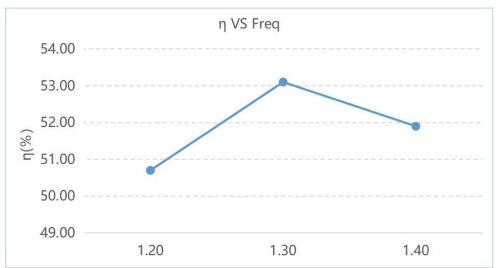


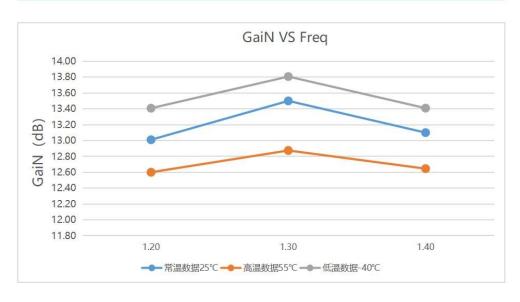


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# **Typical Curves**





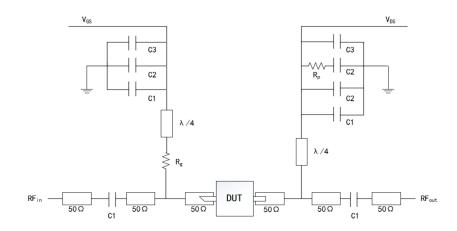




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# **Recommended Application Circuit**



#### **DUT: Device Under Test**

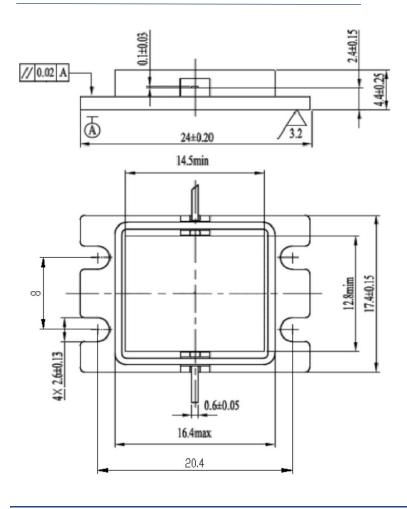
C1:20pF Rp:51 $\Omega$  C2:1000pF Rg:15 $\Omega$ 

C3:100uF

#### **ESD Level**

ESD	Class III	2000V
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#### **Overall Dimensions**



### **Using Notes:**

- During transportation and storage, ensure proper drying.
- During the use and assembly of the chip, take precautions against static electricity. Wear a grounded anti-static wristband.
- When powering on, apply gate voltage first, then apply leakage voltage.